

High Luminous Efficacy Warm White LED Emitter

LZ4-00WW00

Key Features

- High Luminous Efficacy 10W Warm White LED
- Ultra-small foot print 7.0mm x 7.0mm
- Surface mount ceramic package with integrated glass lens
- Very low Thermal Resistance (1.1°C/W)
- Individually addressable die
- Very high Luminous Flux density
- Spatial color uniformity across radiation pattern
- JEDEC Level 1 for Moisture Sensitivity Level
- Autoclave complaint (JEDEC JESD22-A102-C)
- Lead (Pb) free and RoHS compliant
- Reflow solderable (up to 6 cycles)
- Emitter available on Standard MCPCB (optional)

Typical Applications

- General Lighting
- Museum Lighting
- Retail & Display Lighting
- Hospitality Lighting
- Accent & Task Lighting
- Architectural Detail Lighting

Description

The LZ4-00WW00 Warm White LED emitter provides 10W power in an extremely small package. With a 7.0mm x 7.0mm ultra-small footprint, this package provides exceptional luminous flux density. LED Engin's patent-pending thermally insulated phosphor layers provide spatial color uniformity across the radiation pattern and a consistent CCT over time and temperature. LED Engin's LZ4-00WW00 LED offers ultimate design flexibility with individually addressable die. The high quality materials used in the package are chosen to optimize light output and minimize stresses which results in monumental reliability and lumen maintenance. The robust product design thrives in outdoor applications with high ambient temperatures and high humidity.

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Part number options

Base part number

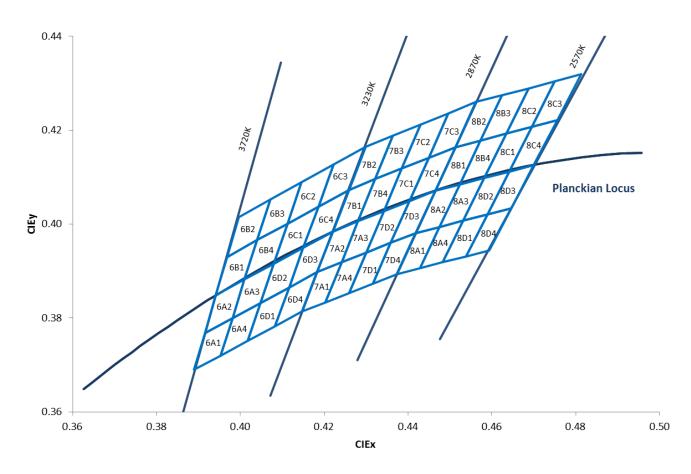
Part number	Description
LZ4-00WW00-xxxx	LZ4 emitter
LZ4-40WW00-xxxx	LZ4 emitter on Standard Star 1 channel MCPCB

Bin kit option codes

WW, Warm-White (2700K – 3500K)					
Kit number suffix	Min flux Bin	Color Bin Ranges	Description		
0027	т	8A1, 8A2, 8B1, 8B2, 8A4, 8A3, 8B4, 8B3, 8D1, 8D2, 8C1, 8C2, 8D4, 8D3, 8C4, 8C3	full distribution flux; 2700K ANSI CCT bin		
0227	Т	8A2, 8B1, 8A3, 8B4, 8D2, 8C1, 8D3, 8C4	full distribution flux; 2700K ANSI CCT half bin		
0427	Т	8A3, 8B4, 8D2, 8C1	full distribution flux; 2700K ANSI CCT quarter bin		
0030	т	7A1, 7A2, 7B1, 7B2, 7A4, 7A3, 7B4, 7B3, 7D1, 7D2, 7C1, 7C2, 7D4, 7D3, 7C4, 7C3	full distribution flux; 3000K ANSI CCT bin		
0230	т	7A2, 7B1, 7A3, 7B4, 7D2, 7C1, 7D3, 7C4	full distribution flux; 3000K ANSI CCT half bin		
0430	Т	7A3, 7B4, 7D2, 7C1	full distribution flux; 3000K ANSI CCT quarter bin		
0035	т	6A1, 6A2, 6B1, 6B2, 6A4, 6A3, 6B4, 6B3, 6D1, 6D2, 6C1, 6C2, 6D4, 6D3, 6C4, 6C3	full distribution flux; 3500K ANSI CCT bin		
0235	Т	6A2, 6B1, 6A3, 6B4, 6D2, 6C1, 6D3, 6C4	full distribution flux; 3500K ANSI CCT half bin		
0435	т	6A3, 6B4, 6D2, 6C1	full distribution flux; 3500K ANSI CCT quarter bin		



Warm White Chromaticity Groups



Standard Chromaticity Groups plotted on excerpt from the CIE 1931 (2°) x-y Chromaticity Diagram. Coordinates are listed below in the table.



Warm White Bin Coordinates

Bin code	CIEx	CIEy	Bin code	CIEx	CIEy	Bin code	CIEx	CIEy	Bin code	CIEx	CIEy
	0.3889	0.369		0.3915	0.3768		0.3941	0.3848		0.3968	0.393
	0.3915	0.3768		0.3941	0.3848		0.3968	0.393		0.3996	0.4015
6A1	0.3981	0.38	6A2	0.401	0.3882	6B1	0.404	0.3966	6B2	0.4071	0.4052
	0.3953	0.372		0.3981	0.38		0.401	0.3882		0.404	0.3966
	0.3889	0.369		0.3915	0.3768		0.3941	0.3848		0.3968	0.393
	0.3953	0.372		0.3981	0.38		0.401	0.3882		0.404	0.3966
	0.3981	0.38		0.401	0.3882		0.404	0.3966		0.4071	0.4052
6A4	0.4048	0.3832	6A3	0.408	0.3916	6B4	0.4113	0.4001	6B3	0.4146	0.4089
	0.4017	0.3751		0.4048	0.3832		0.408	0.3916		0.4113	0.4001
	0.3953	0.372		0.3981	0.38		0.401	0.3882		0.404	0.3966
	0.4017	0.3751		0.4048	0.3832		0.408	0.3916		0.4113	0.4001
	0.4048	0.3832		0.408	0.3916		0.4113	0.4001		0.4146	0.4089
6D1	0.4116	0.3865	6D2	0.415	0.395	6C1	0.4186	0.4037	6C2	0.4222	0.4127
	0.4082	0.3782		0.4116	0.3865		0.415	0.395		0.4186	0.4037
	0.4017	0.3751		0.4048	0.3832		0.408	0.3916		0.4113	0.4001
	0.4082	0.3782		0.4116	0.3865		0.415	0.395		0.4186	0.4037
	0.4116	0.3865		0.415	0.395		0.4186	0.4037		0.4222	0.4127
6D4	0.4183	0.3898	6D3	0.4221	0.3984	6C4	0.4259	0.4073	6C3	0.4299	0.4165
	0.4147	0.3814		0.4183	0.3898		0.4221	0.3984		0.4259	0.4073
	0.4082	0.3782		0.4116	0.3865		0.415	0.395		0.4186	0.4037
	0.4147	0.3814		0.4183	0.3898		0.4221	0.3984		0.4259	0.4073
	0.4183	0.3898		0.4221	0.3984	_	0.4259	0.4073	_	0.4299	0.4165
7A1	0.4242	0.3919	7A2	0.4281	0.4006	7B1	0.4322	0.4096	7B2	0.4364	0.4188
	0.4203	0.3833	_	0.4242	0.3919	_	0.4281	0.4006		0.4322	0.4096
	0.4147	0.3814	-	0.4183	0.3898		0.4221	0.3984		0.4259	0.4073
	0.4203	0.3833		0.4242	0.3919		0.4281	0.4006		0.4322	0.4096
	0.4242	0.3919	-	0.4281	0.4006		0.4322	0.4096		0.4364	0.4188
7A4	0.43	0.3939	7A3 0.4342 0.4028		0.4385	0.4119	7B3	0.443	0.4212		
	0.4259	0.3853	1110	0.43 0.3939		0.4342	0.4028		0.4385	0.4119	
	0.4203	0.3833		0.3919	-	0.4281	0.4006	-	0.4322	0.4096	
	0.4259	0.3853		0.4242	0.3939		0.4342	0.4000		0.4385	0.4030
	0.4255	0.3939	-	0.4342	0.4028	7C1	0.4385	0.4119	7C2	0.430	0.4212
7D1	0.4359	0.396	7D2	0.4403	0.4049		0.4449	0.4141		0.4496	0.4236
/01	0.4335	0.3873	102	0.4359	0.396	/01	0.4403	0.4049		0.4449	0.4141
	0.4259	0.3853		0.4355	0.3939		0.4342	0.4045		0.4385	0.4119
	0.4316	0.3873		0.4359	0.396		0.4403	0.4049		0.4449	0.4141
	0.4359	0.396		0.4403	0.4049		0.4449	0.4141		0.4496	0.4141
7D4	0.4333	0.3981	7D3	0.4465	0.4071	7C4	0.4513	0.4141	7C3	0.4562	0.4250
704	0.4373	0.3893	703	0.4418	0.3981	/04	0.4465	0.4071	/05	0.4513	0.4164
	0.4316	0.3873		0.4359	0.396		0.4403	0.4071		0.4449	0.4104
	0.4373	0.3893		0.4333	0.3981		0.4465	0.4045		0.4443	0.4141
	0.4373	0.3981	-	0.4418	0.3981		0.4513	0.4071	_	0.4513	0.4104
8A1	0.4418	0.3994	8A2	0.4403	0.4071	8B1	0.4513	0.4104	8B2	0.4502	0.420
OAT	0.4475	0.3994	0AZ	0.4323	0.3994	ODI	0.4573	0.4178	ODZ	0.4624	0.4274
			-			_			_		-
	0.4373	0.3893		0.4418	0.3981		0.4465	0.4071		0.4513	0.4164
	0.4428	0.3906	_	0.4475	0.3994		0.4523	0.4085			0.4178
0 A A	0.4475	0.3994	017	0.4523	0.4085	004	0.4573	0.4178	000	0.4624	0.4274
8A4	0.4532	0.4008	8A3	0.4582	0.4099	8B4	0.4634	0.4193	8B3	0.4687	0.4289
	0.4483	0.3919	-		0.4008	_	0.4582	0.4099	-	0.4634	0.4193
	0.4428	0.3906		0.4475	0.3994		0.4523	0.4085		0.4573	0.4178
	0.4483	0.3919	-	0.4532	0.4008	_	0.4582	0.4099	_	0.4634	0.4193
	0.4532	0.4008		0.4582	0.4099		0.4634	0.4193		0.4687	0.4289
8D1	0.4589	0.4021	8D2	0.4641	0.4112	8C1	0.4695	0.4207	8C2	0.475	0.4304
	0.4538	0.3931	_	0.4589	0.4021	_	0.4641	0.4112	_	0.4695	0.4207
	0.4483	0.3919		0.4532	0.4008		0.4582	0.4099		0.4634	0.4193
	0.4538	0.3931		0.4589	0.4021		0.4641	0.4112		0.4695	0.4207
	0.4589	0.4021		0.4641	0.4112		0.4695	0.4207		0.475	0.4304
8D4	0.4646	0.4034	8D3	0.47	0.4126	8C4	0.4756	0.4221	8C3	0.4813	0.4319
	0.4593	0.3944		0.4646	0.4034		0.47	0.4126		0.4756	0.4221
	0.4538	0.3931		0.4589	0.4021		0.4641	0.4112		0.4695	0.4207

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Luminous Flux Bins

	Table 1:	
	Minimum	Maximum
Bin Code	Luminous Flux (Φ_V)	Luminous Flux (Φ_V)
Bin code	@ I _F = 700mA ^[1,2]	@ I _F = 700mA ^[1,2]
	(Im)	(lm)
Т	445	556
U	556	695

Notes for Table 1:

1. Luminous flux performance guaranteed within published operating conditions. LED Engin maintains a tolerance of ± 10% on flux measurements.

2. Future products will have even higher levels of luminous flux performance. Contact LED Engin Sales for updated information.

Forward Voltage Bins

	Table 2:		
	Minimum	Maximum	
Dia Cada	Forward Voltage (V _F)	Forward Voltage (V _F)	
Bin Code	@ I _F = 700mA ^[1,2]	@ I _F = 700mA ^[1,2]	
	(V)	(V)	
0	12.80	16.64	

Notes for Table 2:

1. LED Engin maintains a tolerance of $\pm 0.04V$ for forward voltage measurements.

2. Forward Voltage is binned with all four LED dice connected in series.



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
DC Forward Current at T _{jmax} =135°C ^[1]	١ _F	1200	mA
DC Forward Current at T _{jmax} =150°C ^[1]	I _F	1000	mA
Peak Pulsed Forward Current ^[2]	I _{FP}	1500	mA
Reverse Voltage	V _R	See Note 3	V
Storage Temperature	T_{stg}	-40 ~ +150	°C
Junction Temperature	TJ	150	°C
Soldering Temperature ^[4]	T _{sol}	260	°C
Allowable Reflow Cycles		6	
Autoclave Conditions ^[5]		121°C at 2 ATM,	
Autoclave conditions		100% RH for 168 hours	
ECD Consistivity ^[6]		> 8,000 V HBM	
ESD Sensitivity ^[6]		Class 3B JESD22-A114-D	

Notes for Table 3:

1. Maximum DC forward current (per die) is determined by the overall thermal resistance and ambient temperature.

Follow the curves in Figure 10 for current derating.

2: Pulse forward current conditions: Pulse Width \leq 10msec and Duty cycle \leq 10%.

3. LEDs are not designed to be reverse biased.

4. Solder conditions per JEDEC 020D. See Reflow Soldering Profile Figure 5.

5. Autoclave Conditions per JEDEC JESD22-A102-C.

 LED Engin recommends taking reasonable precautions towards possible ESD damages and handling the LZ4-00WW00 in an electrostatic protected area (EPA). An EPA may be adequately protected by ESD controls as outlined in ANSI/ESD S6.1.

Optical Characteristics @ T_c = 25°C

Table 4:

Parameter	Symbol	Typical	Unit
Luminous Flux (@ I _F = 700mA) ^[1]	Φv	550	lm
Luminous Flux (@ I _F = 1000mA) ^[1]	Φv	700	lm
Luminous Efficacy (@ I _F = 350mA)		72	lm/W
Correlated Color Temperature ^[2]	ССТ	3000	К
Color Rendering Index (CRI / R9)	Ra	85	
Viewing Angle ^[3]	2O _{1/2}	105	Degrees
Total Included Angle ^[4]	Θ _{0.9V}	135	Degrees

Notes for Table 4:

1. Luminous flux typical value is for all four LED dice operating concurrently at rated current.

2. Typical Color Rendering Index (CRI) is 80.

3. Viewing Angle is the off axis angle from emitter centerline where the luminous intensity is ½ of the peak value.

4. Total Included Angle is the total angle that includes 90% of the total luminous flux.

Electrical Characteristics @ T_c = 25°C

	Table 5:			
Parameter	Symbol	Typical	Unit	
Forward Voltage (@ I _F = 700mA) ^[1]	V _F	14.0	V	
Forward Voltage (@ $I_F = 1000 \text{ mA}$) ^[1]	V _F	14.6	V	
Temperature Coefficient of Forward Voltage ⁽¹⁾	$\Delta V_F / \Delta T_J$	-11.9	mV/°C	
Thermal Resistance (Junction to Case)	RΘ _{J-C}	1.1	°C/W	

Notes for Table 5:

1. Forward Voltage typical value is for all four LED dice connected in series.

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IPC/JEDEC Moisture Sensitivity Level

				Soak Req	uirements	
	Floo	r Life	Stan	dard	Accel	erated
Level	Time	Conditions	Time (hrs)	Conditions	Time (hrs)	Conditions
1	Unlimited	≤ 30°C/ 85% RH	168 +5/-0	85°C/ 85% RH	n/a	n/a

Table 6 - IPC/JEDEC J-STD-20 MSL Classification:

Notes for Table 6:

1. The standard soak time is the sum of the default value of 24 hours for the semiconductor manufacturer's exposure time (MET) between bake and bag and the floor life of maximum time allowed out of the bag at the end user of distributor's facility.

Average Lumen Maintenance Projections

Lumen maintenance generally describes the ability of a lamp to retain its output over time. The useful lifetime for solid state lighting devices (Power LEDs) is also defined as Lumen Maintenance, with the percentage of the original light output remaining at a defined time period.

Based on long-term WHTOL testing, LED Engin projects that the LZ Series will deliver, on average, 70% Lumen Maintenance at 65,000 hours of operation at a forward current of 700 mA per die. This projection is based on constant current operation with junction temperature maintained at or below 125°C.



INDEX MARK 1 3 3 A В 9 D 4 8 1.9 11 7 6 5 5 6 THERMAL SLUG

Ø**6.2**

Mechanical Dimensions (mm)

Pin Out					
Pad	Die	Function			
1	Α	Anode			
2	А	Cathode			
3	В	Anode			
4	В	Cathode			
5	С	Anode			
6	С	Cathode			
7	D	Anode			
8	D	Cathode			
9 ^[2]	n/a	Thermal			

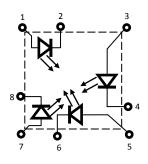


Figure 1: Package outline drawing.

SUBSTRATE

8

7

LENS

Notes for Figure 1:

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1. Unless otherwise noted, the tolerance = \pm 0.20 mm.

2. Thermal contact, Pad 9, is electrically neutral.

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Recommended Solder Pad Layout (mm)

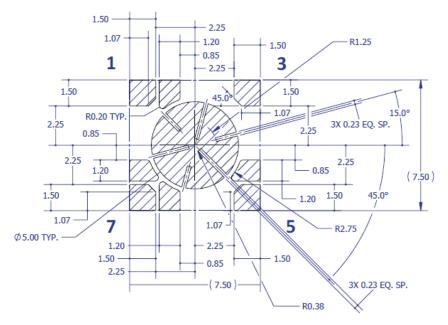


Figure 2a: Recommended solder pad layout for anode, cathode, and thermal pad.

Note for Figure 2a:

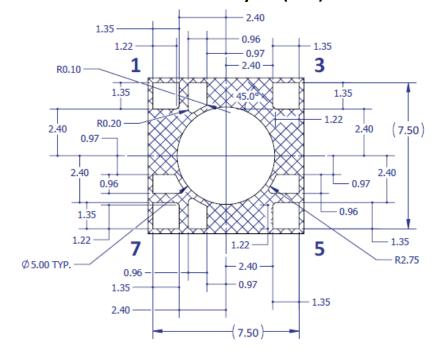
1. Unless otherwise noted, the tolerance = ± 0.20 mm.

2. This pad layout is "patent pending".

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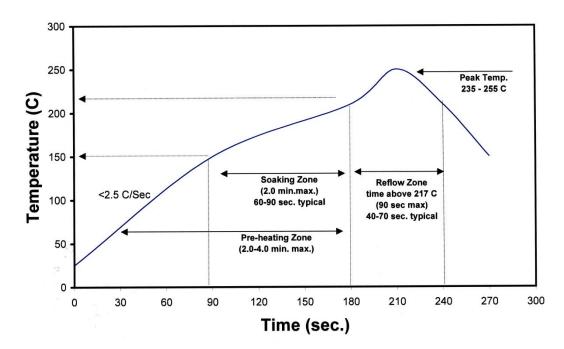


Recommended Solder Mask Layout (mm)

Figure 2b: Recommended solder mask opening (hatched area) for anode, cathode, and thermal pad.

Note for Figure 2b:

1. Unless otherwise noted, the tolerance = ± 0.20 mm.



Reflow Soldering Profile

Figure 3: Reflow soldering profile for lead free soldering.

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Typical Radiation Pattern

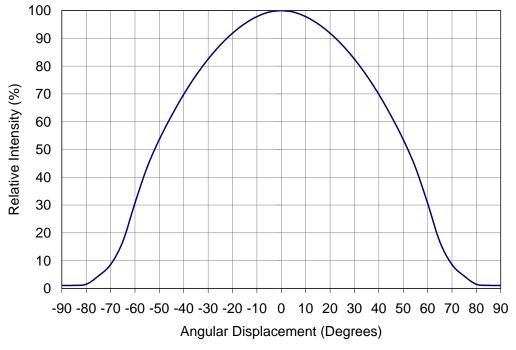


Figure 4: Typical representative spatial radiation pattern.

Typical Relative Spectral Power Distribution

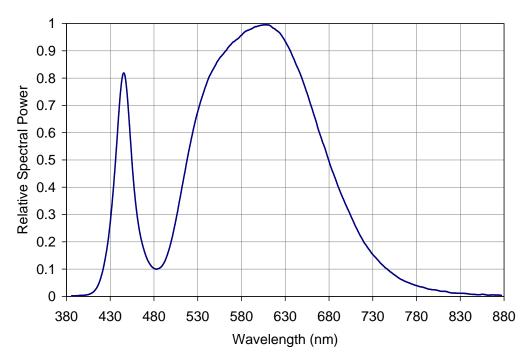


Figure 5: Typical relative spectral power vs. wavelength @ $T_c = 25^{\circ}C$.

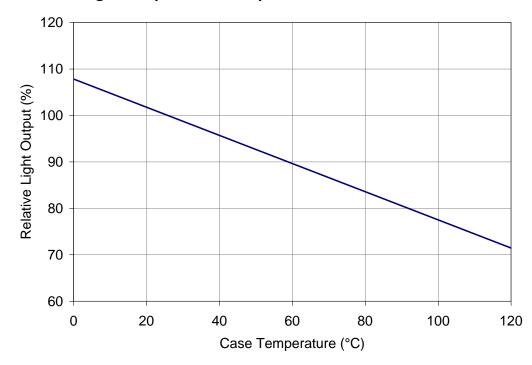
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Relative Light Output (%) I_F - Forward Current (mA)

Typical Relative Light Output

Figure 6: Typical relative light output vs. forward current @ $T_c = 25^{\circ}C$.



Typical Relative Light Output over Temperature

Figure 7: Typical relative light output vs. case temperature.

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Typical Forward Current Characteristics

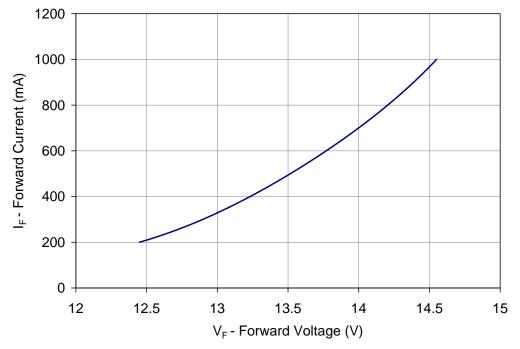
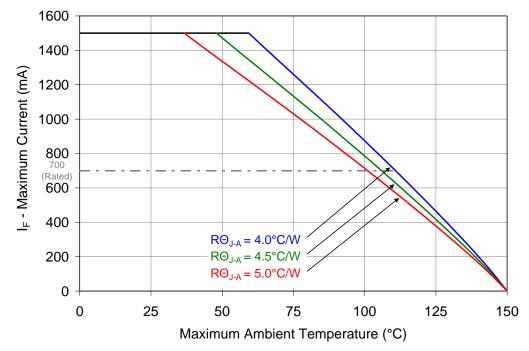


Figure 8: Typical forward current vs. forward voltage @ T_c = at 25°C.

Note for Figure 8:

1. Forward Voltage curve assumes that all four LED dice are connected in series.

Current De-rating





Notes for Figure 9:

1. Maximum current assumes that all four LED dice are operating concurrently at the same current.

2. RO_{J-C} [Junction to Case Thermal Resistance] for the LZ4-00CW10 is typically 1.1°C/W.

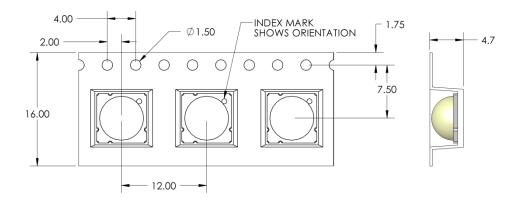
3. $R\Theta_{J-A}$ [Junction to Ambient Thermal Resistance] = $R\Theta_{J-C} + R\Theta_{C-A}$ [Case to Ambient Thermal Resistance].

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Emitter Tape and Reel Specifications (mm)



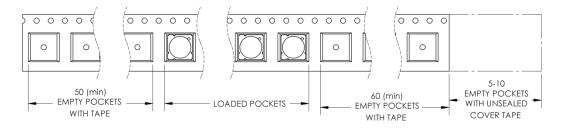


Figure 10: Emitter carrier tape specifications (mm).

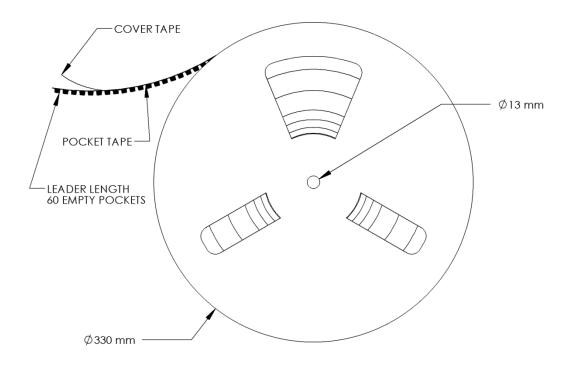


Figure 11: Emitter Reel specifications (mm).

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LZ4 MCPCB Family

Part number	Type of MCPCB	Diameter (mm)	Emitter + MCPCB Thermal Resistance (°C/W)	Typical V _f (V)	Typical I _f (mA)
LZ4-4xxxxx	1-channel	19.9	1.1 + 1.1 = 2.2	14.0	700

Mechanical Mounting of MCPCB

- MCPCB bending should be avoided as it will cause mechanical stress on the emitter, which could lead to substrate cracking and subsequently LED dies cracking.
- To avoid MCPCB bending:
 - Special attention needs to be paid to the flatness of the heat sink surface and the torque on the screws.
 - Care must be taken when securing the board to the heat sink. This can be done by tightening three M3 screws (or #4-40) in steps and not all the way through at once. Using fewer than three screws will increase the likelihood of board bending.
 - It is recommended to always use plastics washers in combinations with the three screws.
 - If non-taped holes are used with self-tapping screws, it is advised to back out the screws slightly after tightening (with controlled torque) and then re-tighten the screws again.

Thermal interface material

- To properly transfer heat from LED emitter to heat sink, a thermally conductive material is required when mounting the MCPCB on to the heat sink.
- There are several varieties of such material: thermal paste, thermal pads, phase change materials and thermal
 epoxies. An example of such material is Electrolube EHTC.
- It is critical to verify the material's thermal resistance to be sufficient for the selected emitter and its operating conditions.

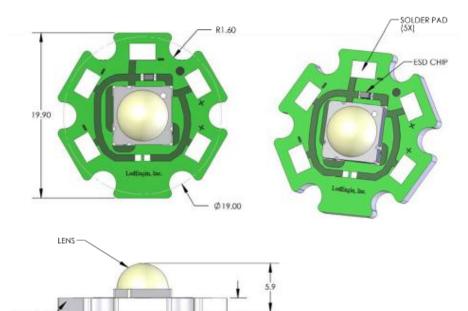
Wire soldering

- To ease soldering wire to MCPCB process, it is advised to preheat the MCPCB on a hot plate of 125-150°C.
 Subsequently, apply the solder and additional heat from the solder iron will initiate a good solder reflow. It is recommended to use a solder iron of more than 60W.
- It is advised to use lead-free, no-clean solder. For example: SN-96.5 AG-3.0 CU 0.5 #58/275 from Kester (pn: 24-7068-7601)



LZ4-4xxxxx

1 channel, Standard Star MCPCB (1x4) Dimensions (mm)



Notes:

BOARD

- Unless otherwise noted, the tolerance = ± 0.2 mm.
- Slots in MCPCB are for M3 or #4-40 mounting screws.
- LED Engin recommends plastic washers to electrically insulate screws from solder pads and electrical traces.

1.70

- Electrical connection pads on MCPCB are labeled "+" for Anode and "-" for Cathode
- LED Engin recommends thermal interface material when attaching the MCPCB to a heatsink
- The thermal resistance of the MCPCB is: ROC-B 1.1°C/W

Components used

MCPCB:	HT04503	(Bergquist)
ESD chips:	BZX585-C30	(NXP, for 4 LED dies in series)

Pad layout			
Ch.	MCPCB Pad	String/die	Function
1	-		Cathode -
	+	1/ABCD	Anode +



Company Information

LED Engin, based in California's Silicon Valley, develops, manufactures, and sells advanced LED emitters, optics and light engines to create uncompromised lighting experiences for a wide range of entertainment, architectural, general lighting and specialty applications. LuxiGen[™] multi-die emitter and secondary lens combinations reliably deliver industry-leading flux density, upwards of 5000 quality lumens to a target, in a wide spectrum of colors including whites, tunable whites, multi-color and UV LEDs in a unique patented compact ceramic package. Our LuxiTune[™] series of tunable white lighting modules leverage our LuxiGen emitters and lenses to deliver quality, control, freedom and high density tunable white light solutions for a broad range of new recessed and downlighting applications. The small size, yet remarkably powerful beam output and superior in-source color mixing, allows for a previously unobtainable freedom of design wherever high-flux density, directional light is required.

LED Engin is committed to providing products that conserve natural resources and reduce greenhouse emissions.

LED Engin reserves the right to make changes to improve performance without notice.

Please contact <u>sales@ledengin.com</u> or (408) 922-7200 for more information.

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